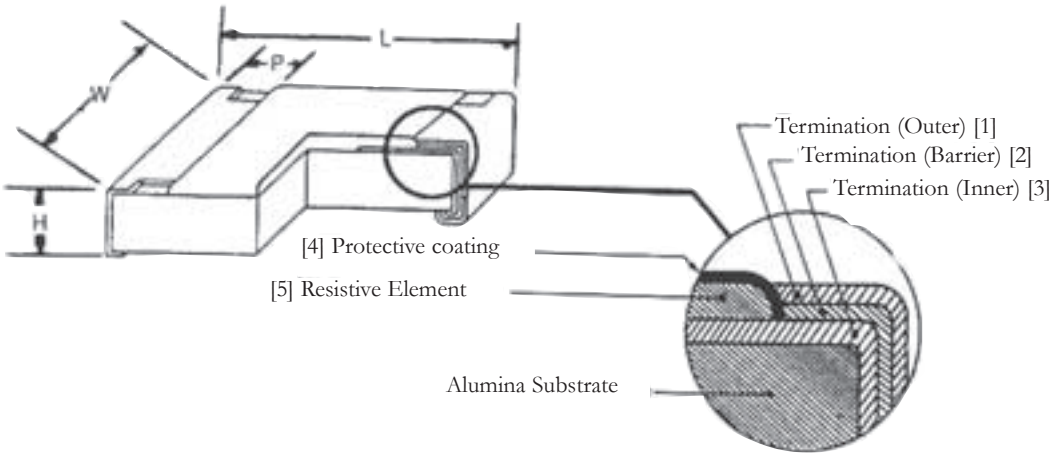
LEADFREE
RoHS Compliant

FEATURES

- Available sizes - 0402, 0603, 0805, 1206, 1210, 2010, 2512
- Wide range of wattages and resistance values
- Excellent solderability
- Nickel barrier for leaching control
- Paper and embossed plastic tape packaging

CONSTRUCTION AND TERMINATION DETAILS



[1] Solder Plate, 90% Sn, 10% Pb
Tin / Lead

[2] Barrier, Ni
Nickel

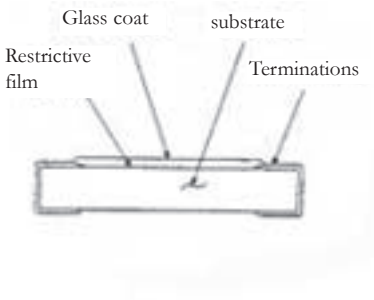
[3] Electrode Ag/Pd
Silver / Palladium

[4] Protective Layer

[5] Resistive Element

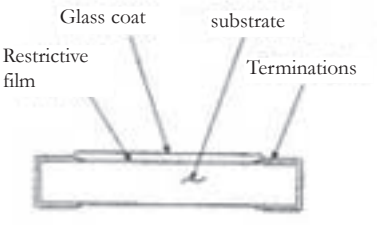
MATERIAL CHARACTERISTICS (THICK & THIN FILM CHIP)

Thick Film Chip Resistors



Feature	Feature	Remarks (Reference Only)
Substrate	Alumina Porcelain	Purity 96% min.
Resistive Film	Ruthenium-Oxide Film	20 Microns Thick
Coating	Boro-Silicated Acid Lead Glass	20 Microns Thick
Terminations	90/10 Tin-Lead (Electrical Plated) over	3 Microns Thick
	Nickel (Electrical Plated) over	3 Microns Thick
	AG-PD (Silver-Palladium[Glaze printed])	8 Microns Thick

Thin Film Chip Resistors



Feature	Feature	Remarks (Reference Only)
Substrate	Alumina Porcelain	Purity 96% min.
Resistive Film	Nickel-Chromium Film	20 Microns Thick
Coating	Boro-Silicated Acid Lead Glass	20 Microns Thick
Terminations	90/10 Tin-Lead (Electrical Plated) over	3 Microns Thick
	Nickel (Electrical Plated) over	3 Microns Thick
	AG-PD (Silver-Palladium[Glaze printed])	8 Microns Thick